



PRESS RELEASE

For Release July 24, 2023

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TopLine Exhibiting at CHIPcon July 24-27

Irvine, California, USA - TopLine is exhibiting at CHIPCon in San Jose, California July 24-27, 2023, Martin Hart, CEO of TopLine, has announced.

Formerly IMAPS aSIP, the new CHIPcon is billed as the top global event for Chiplet and Heterogeneous Integration Packaging (CHIP), covering advanced technology developments and solutions, device integration strategies, and business trends. The IMAPS CHIPcon conference will focus exclusively on innovative device integration technology developments, solutions, and business trends. For more information about the conference, visit <https://imaps.org/page/CHIPcon2023>.



*Martin Hart, CEO of
TopLine Corporation*

TopLine manufactures next generation solder columns for large-sized 2.5D Heterogeneous BGA packages, and provides Daisy Chain packages for engineering development, profiling and practice. TopLine products provide hands-on learning for engineers. To learn more, visit www.cpga.tv or call (+1) 800 – 776-9888.

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